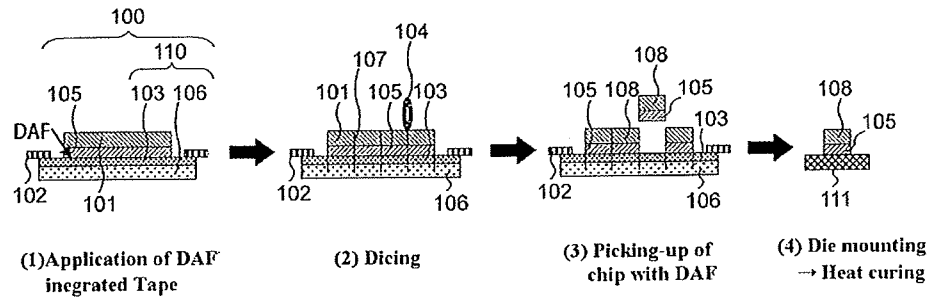
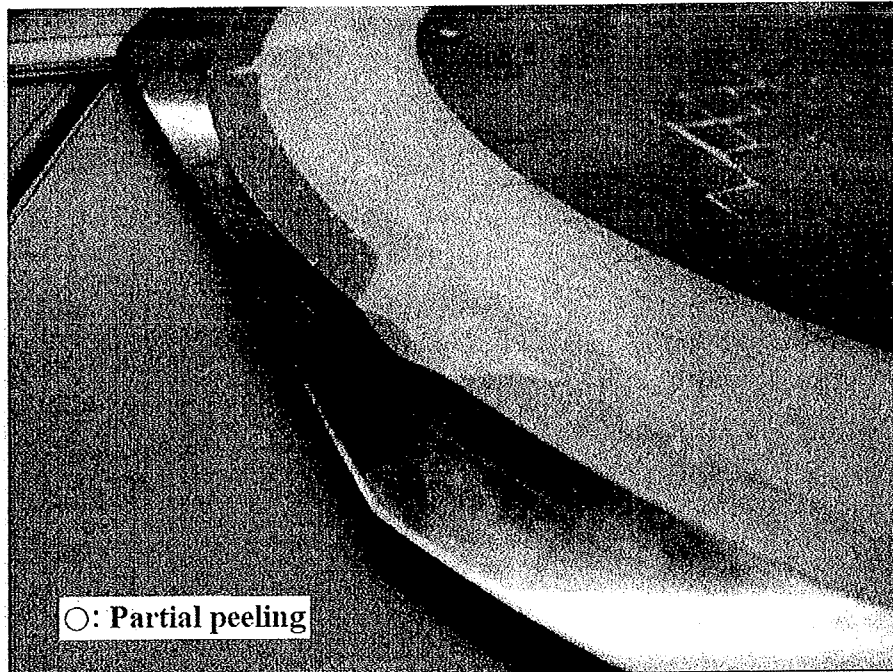


[Fig. 1]

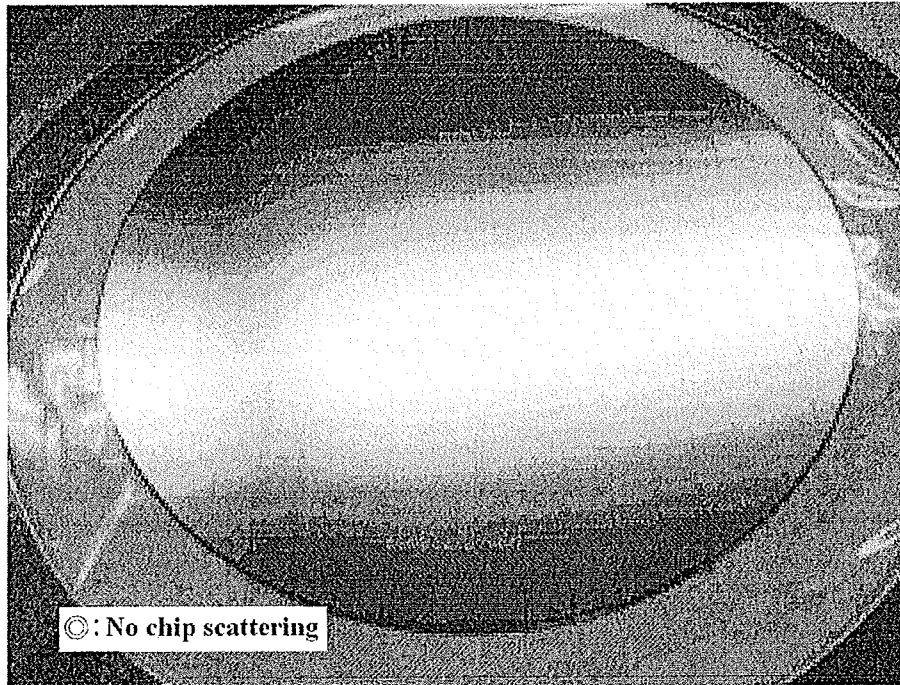
DAF Usage Process

[Fig. 2]



- ① Ring frame fixation
- ◎: No peeling
- : Partial peeling (hanging)
- ×: Tape was peeled from frame

[Fig. 3]



Chip retention

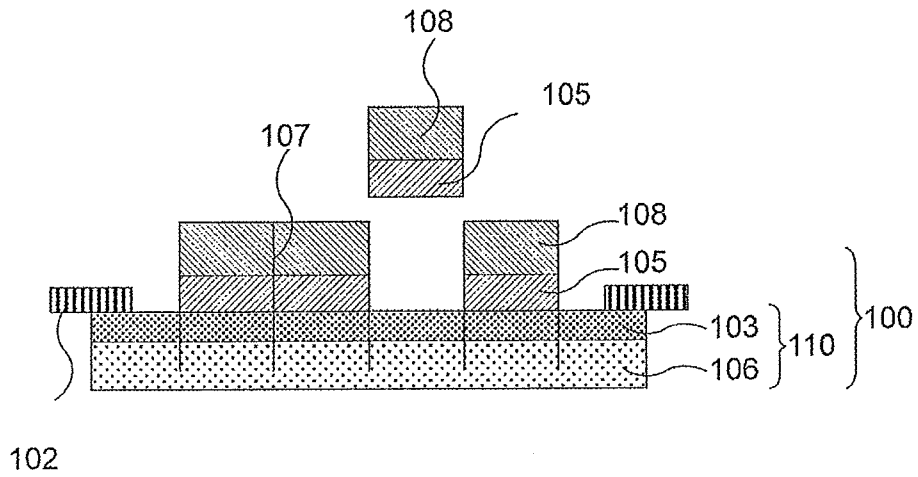
◎: Chip scattering was less than 5%

○: Chip scattering was at least 5% to less than 10%

×: Chip scattering was at least 10%

[Fig. 4]

(3) from FIG. 1

**Pick-up properties**

- ◎: At least 95% were picked-up
- : At least 80% to less than 95% were picked-up
- ×: Less than 80% were picked up